BTA216 series D, E and F

GENERAL DESCRIPTION

QUICK REFERENCE DATA

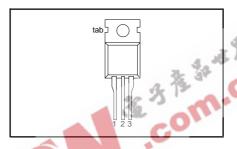
Passivated guaranteed commutation triacs in a plastic envelope intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
	BTA216- BTA216- BTA216-	600D 600E 600F	- 800E 800F	
V_{DRM}	Repetitive peak off-state	600	800	V
I _{T(RMS)} I _{TSM}	voltages RMS on-state current Non-repetitive peak on-state current	16 140	16 140	A A

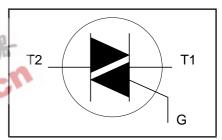
PINNING - TO220AB

PIN	DESCRIPTION			
1	main terminal 1			
2	main terminal 2			
3	gate			
tab	main terminal 2			

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MA	X.	UNIT
V_{DRM}	Repetitive peak off-state voltages			-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-	16	6	Α
I _{TSM}	Non-repetitive peak on-state current	$T_{mb} \le 99$ °C full sine wave; $T_j = 25$ °C prior to surge $t = 20$ ms	-	14		Ą
l ² t	I ² t for fusing	t = 16.7 ms t = 10 ms	-	15		A^2 s
dl _⊤ /dt	Repetitive rate of rise of on-state current after	$I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A}; $ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	-	98 100		A/μs
I _{GM} V _{GM} P _{GM} P _{G(AV)}	triggering Peak gate current Peak gate voltage Peak gate power Average gate power	over any 20 ms period		2 5 5 0.9		A V W
T_{stg}^{stg}	Storage temperature Operating junction temperature	11-2	-40 -	15 12		°C

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¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 $A/\mu s$.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle in free air	1 1 1	- - 60	1.2 1.7 -	K/W K/W K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.		MAX.		UNIT
		BTA216-			D	E	F	
I _{GT}	Gate trigger current ²	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $T2 + G +$ $T2 + G T2 - G -$	-	1.3 2.6 3.4	5 5 5	10 10 10	25 25 25	mA mA mA
I _L	Latching current	V _D = 12 V; I _{GT} = 0.1 A T2+ G+ T2+ G- T2- G-	海雪	10.2 11.3 19.3	15 25 25	25 30 30	30 40 40	mA mA mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	0-	8	15	25	30	mA
					D, E, F			
V_{T}	On-state voltage Gate trigger voltage	$I_T = 20 \text{ A}$ $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	- - 0.25	1.2 0.7 0.4		1.5 1.5 -		V V
I _D	Off-state leakage current	$T_j = 125 \text{ °C}$ $V_D = V_{DRM(max)};$ $T_j = 125 \text{ °C}$	-	0.1		0.5		mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
		BTA216-	D	Е	F	D		
dV _D /dt	Critical rate of rise of off-state voltage	V _{DM} = 67% V _{DRM(max)} ; T _j = 110 °C; exponential waveform; gate open circuit	30	60	70	65	-	V/μs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 110 ^{\circ}\text{C};$ $I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	2.5	4.7	9.5	7.5	-	A/ms
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 110 ^{\circ}\text{C};$ $I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 0.1 \text{V}/\mu\text{s}; gate}$ open circuit	12	40	50	100	-	A/ms
			D, E, F					
t _{gt}	Gate controlled turn-on time	$egin{aligned} I_{TM} = 20 \text{ A; } V_D = V_{DRM(max)}; \\ I_G = 0.1 \text{ A; } dI_G/dt = 5 \text{ A/}\mu s \end{aligned}$	-	-	-	2	-	μs

² Device does not trigger in the T2-, G+ quadrant.

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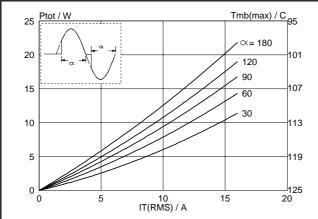


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

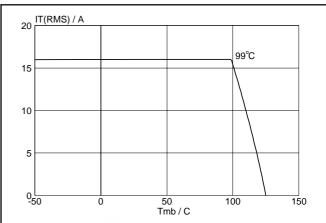


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

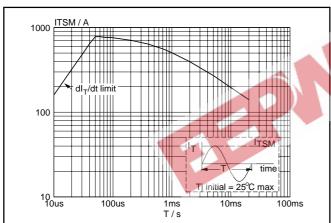


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

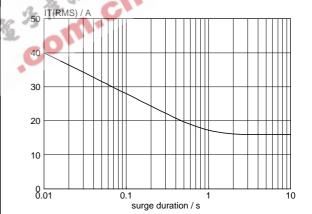


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 99$ °C.

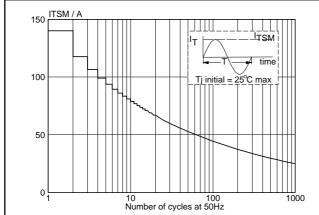


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

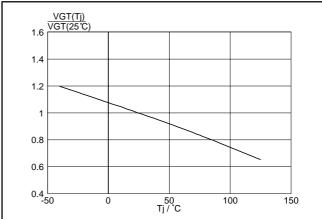
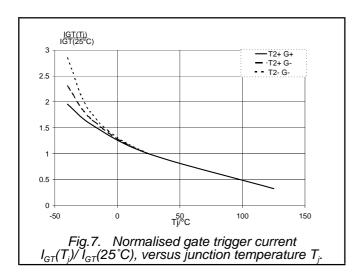
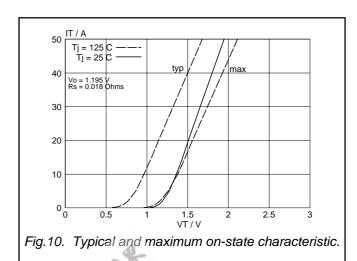
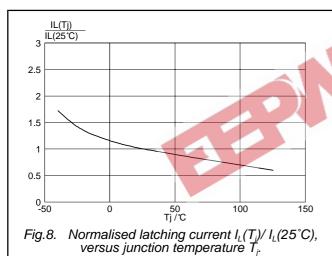


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_j .

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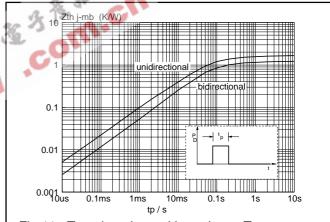


Fig.11. Transient thermal impedance $Z_{th j-mb}$, versus pulse width t_p .

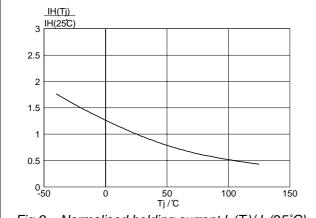
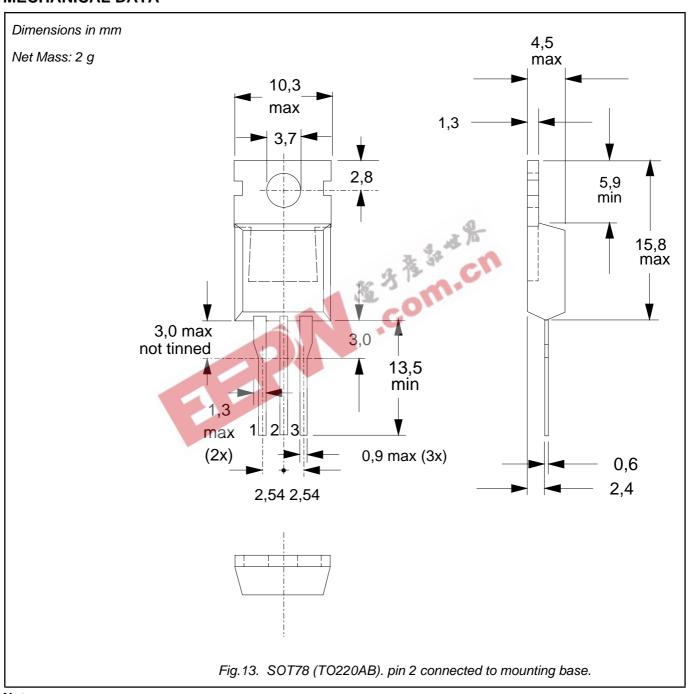


Fig.12. Minimum, critical rate of change of commutating current dI_{com}/dt versus junction temperature, $dV_{com}/dt = 20V/\mu s$.

Fig.9. Normalised holding current $I_H(T_i)/I_H(25^{\circ}\text{C})$, versus junction temperature T_i .

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MECHANICAL DATA



- Refer to mounting instructions for SOT78 (TO220) envelopes.
 Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
1 to the term of the contract					

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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